

导电点胶

FORM IN PLACE (FIP) ELASTOMERS

产品介绍 PRODUCT INTRODUCTION

导电点胶主要有导电填料和树脂等组成，这些树脂在固化后形成了导电胶的分子骨架结构，提供了力学性能和粘接性能保障，并使导电填料粒子形成通道，导电点胶可分为室温固化和高温固化体系，可采用点胶机连续作业。

Form in Place (FIP) Elastomers is mainly composed of conductive filler and resin. After curing, these resins form the molecular skeleton structure of conductive adhesive, provide the guarantee of mechanical properties and bonding properties, and form channels for conductive filler particles. Form in Place (FIP) Elastomers can be divided into room temperature curing and high temperature curing systems, which can be operated continuously by dispensing machine.



产品特点 PRODUCT FEATURE

- 就地成型，减少工艺成本
- 多种导电材质可供选择
- 低应力，高压缩
- Form in Place, Reduce process cost
- Varies of conductive materials are available
- Low stress, high compression

典型应用 TYPICAL APPLICATION

- 光模块
- 汽车电子
- 服务器
- 医疗
- 数据通信
- Optical module
- Automotive electronics
- Server
- Medical industry
- DataCom

产品参数 PRODUCT PARAMETER

产品型号 Models	导电填料 Conductive Filler	固化方式 Curing conditions	固化时间 Curing Time	硬度 Hardness	体积电阻率 Volume Resistivity	屏蔽效果 Adhesion Strength	阻燃等级 Flammability Rating	保质期 Shelf Life
		固化温度	hour@temperature	shoreA	ohm-cm	@200MHz- 10GHz dB	UL-94	-20°C months
EFIP 451H	Ni/C	高温固化	30MIN@150°C	45	0.04	>90	V0	6
EFIP 604R	Ag/Al	常温固化	12H@ 25°C	60	0.008	>100	V0	6
EFIP 602R	Ag/Cu	常温固化	24H@ 25°C	60	0.003	>110	V0	6
EFIP 503R	Ag/Ni	常温固化	24H@ 25°C	50	0.005	>100	V0	6
EFIP 553H	Ag/Ni	高温固化	2H@ 120°C	55	0.01	>100	V0	6